

74HC125

DATASHEET

Specification Revision History:

Version	Date	Description
V1.0	2021/08	New
V1.1	2022/11	Modify Ordering Information
V1.2	2025/02	Modify Ordering Information
V1.3	2025/03	Add application precautions and overall typesetting.

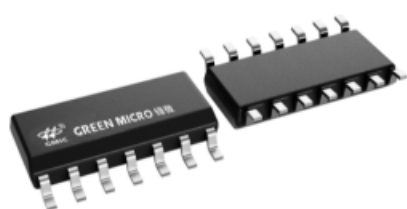
1、General Description

The 74HC125 is a quad buffer/line driver with 3-state outputs controlled by the output enable inputs($\overline{nOE}$). A HIGH on $\overline{nOE}$ causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of Vcc.

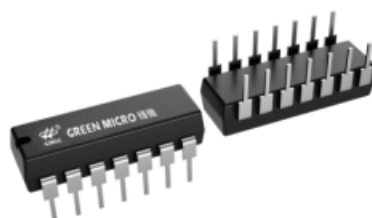
FEATURES

- Input levels:
For 74HC125:CMOS level
- Specified from -40°C to +85°C
- Packaging information: DIP14/SOP14

The appearance of the product



SOP-14



DIP-14

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
SN74HC125DR(GMIC)	SOP-14	74HC125 178	REEL	2500PCS/REEL
SN74HC125N(GMIC)	DIP-14	74HC125 178	TUBE	1000PCS/BOX

2、Block Diagram And Pin Description

2.1、Block Diagram

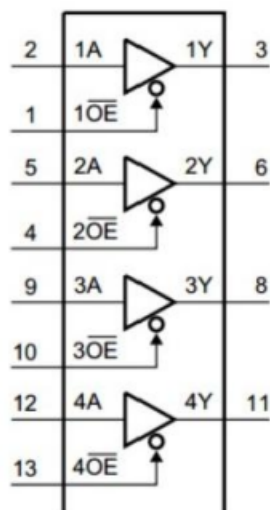


Figure 1.Logic symbol



Figure 2.IEC logic symbol

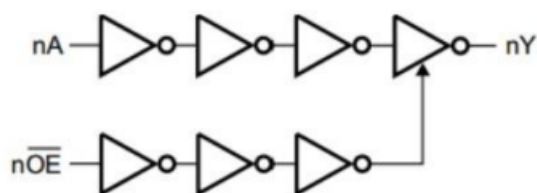
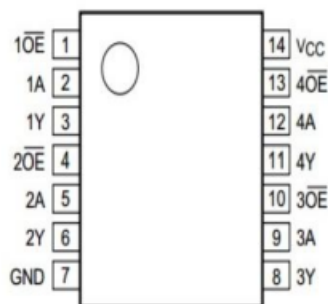


Figure 3.Logic diagram for one gate

2.2 、Pin Configurations



2.3、 Pin Description

Pin No.	Pin Name	Description
1	1 $\overline{OE}$	output enable input(active LOW)
2	1A	data input
3	1Y	data output
4	2 $\overline{OE}$	output enable input(active LOW)
5	2A	data input
6	2Y	data output
7	GND	ground (0V)
8	3Y	data output
9	3A	data input
10	3 $\overline{OE}$	output enable input(active LOW)
11	4Y	data output
12	4A	data input
13	4 $\overline{OE}$	output enable input(active LOW)
14	V _{CC}	supply voltage

2.4、 Function Table

Control	Input	Output
n $\overline{OE}$	nA	nY
L	L	L
L	H	H
H	X	Z

Note:H=HIGH voltage level;L=LOW voltage level;X=don't care;Z=high-impedance OFF-state.

3、Electrical Parameter

3.1、Absolute Maximum Ratings

(Voltages are referenced to GND(ground=0V),unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Max.	Unit
supply voltage	V _{CC}	-		-0.5	+7	V
input clamping current	I _{IK}	V _I <-0.5V or V _I >V _{CC} +0.5V		-	± 20	mA
output clamping current	I _{OK}	V _O <-0.5V or V _O >V _{CC} +0.5V		-	± 20	mA
output current	I _O	-0.5V<V _O <V _{CC} +0.5V		-	± 35	mA
supply current	I _{CC}			-	70	mA
ground current	I _{GND}	-		-70	-	mA
total power dissipation	P _{tot}	-		-	500	mW
storage temperature	T _{stg}			-65	+150	°C
Soldering temperature	T _L	10s	DIP	245		°C
			SOP	250		

Note:

[1] For DIP14 packages:above 70°C the value of P_{tot} derates linearly with 12mW/K.

[2]For SOP14 packages:above 70°C the value of P_{tot} derates linearly with 8mW/K.

3.2、Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
74HC125						
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O		0	-	V_{CC}	V
input transition rise and fall rate	$\Delta t / \Delta V$	$V_{CC} = 2.0V$	-	-	625	ns/V
		$V_{CC} = 4.5V$	-	1.67	139	ns/V
		$V_{CC} = 6.0V$	-	-	83	ns/V
ambient temperature	T_{amb}		-40	-	+85	°C

3.3、Electrical Characteristics

3.3.1、DC Characteristics 1

(Tamb=25°C, voltages are referenced to GND(ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
74HC125							
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0V$		1.5	1.2	-	V
		$V_{CC}=4.5V$		3.15	2.4	-	V
		$V_{CC}=6.0V$		4.2	3.2	-	V
LOW-level input voltage	V_{IL}	$V_{CC}=2.0V$		-	0.8	0.5	V
		$V_{CC}=4.5V$		-	2.1	1.35	V
		$V_{CC}=6.0V$		-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_O=20\mu A; V_{CC}=2.0V$	1.9	2.0	-	V
			$I_O=-20\mu A; V_{CC}=4.5V$	4.4	4.5	-	V
			$I_O=-20\mu A; V_{CC}=6.0V$	5.9	6.0	-	V
			$I_O=-6.0mA; V_{CC}=4.5V$	3.98	4.32	-	V
			$I_O=-7.8mA; V_{CC}=6.0V$	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_O=20\mu A; V_{CC}=2.0V$	-	0	0.1	V
			$I_O=20\mu A; V_{CC}=4.5V$	-	0	0.1	V
			$I_O=20\mu A; V_{CC}=6.0V$	-	0	0.1	V
			$I_O=6.0mA; V_{CC}=4.5V$	-	0.15	0.26	V
			$I_O=7.8mA; V_{CC}=6.0V$	-	0.16	0.26	V
input leakage current	I_I	$V_I=V_{CC} \text{ or } GND;$ $V_{CC}=6.0V$		-		± 0.1	μA
OFF-state output current	I_{OZ}	$V_I=V_{IH} \text{ or } V_{IL}; V_O=V_{CC} \text{ or } GND;$ $V_{CC}=6.0V$		-		± 0.5	μA
supply current	I_{CC}	$V_I=V_{CC} \text{ or } GND; I_O=0A;$ $V_{CC}=6.0V$		-	-	8.0	μA
Input capacitance	C_i	-		-	3.5	-	pF

3.3.2、DC Characteristics 2

(Tamb=-40°C to+85°C,voltages are referenced to GND(ground=0V),unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
74HC125							
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0V$		1.5	-	-	V
		$V_{CC}=4.5V$		3.15	-	-	V
		$V_{CC}=6.0V$		4.2	-	-	V
LOW-level input voltage	V_{IL}	$V_{CC}=2.0V$		-	-	0.5	V
		$V_{CC}=4.5V$			-	1.35	V
		$V_{CC}=6.0V$		-	-	1.8	V
HIGH-level output voltage	V_{OH}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_o=20\mu A; V_{CC}=2.0V$	1.9	-	-	V
			$I_o=20\mu A; V_{CC}=4.5V$	4.4	-	-	V
			$I_o=20\mu A; V_{CC}=6.0V$	5.9	-	-	V
			$I_o=6.0mA; V_{CC}=4.5V$	3.84	-	-	V
			$I_o=7.8mA; V_{CC}=6.0V$	5.34	-	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_o=20\mu A; V_{CC}=2.0V$	-	-	0.1	V
			$I_o=20\mu A; V_{CC}=4.5V$	-	-	0.1	V
			$I_o=20\mu A; V_{CC}=6.0V$	-	-	0.1	V
			$I_o=6.0mA; V_{CC}=4.5V$	-	-	0.33	V
			$I_o=7.8mA; V_{CC}=6.0V$	-	-	0.33	V
input leakage current	I_I	$V_I=V_{CC} \text{ or } GND;$ $V_{CC}=6.0V$		-	-	± 1	μA
OFF-state output current	I_{OZ}	$V_I=V_{IH} \text{ or } V_{IL}; V_o=V_{CC} \text{ or } GND;$ $V_{CC}=6.0V$		-		± 5	μA
supply current	I_{CC}	$V_I=V_{CC} \text{ or } GND; I_o=0A;$ $V_{CC}=6.0V$		-	-	80	μA
Input capacitance	C_I			-	-	-	pF

3.3.3、AC Characteristics 1

(Tamb=25°C, voltages are referenced to GND(ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
74HC125						
nA to nY propagation delay	t_{pd}	see Figure 5	$V_{CC}=2.0V$	-	30	100 ns
			$V_{CC}=4.5V$	-	11	20 ns
			$V_{CC}=5.0V; CL=15pF$	-	9	- ns
			$V_{CC}=6.0V$	-	9	17 ns
$\overline{nOE}$ tonY enable time	t_{en}	see Figure 6	$V_{CC}=2.0V$	-	41	125 ns
			$V_{CC}=4.5V$	-	15	25 ns
			$V_{CC}=6.0V$	-	12	21 ns
$\overline{nOE}$ tonY disable time	t_{dis}	see Figure 6	$V_{CC}=2.0V$	-	41	125 ns
			$V_{CC}=4.5V$	-	15	25 ns
			$V_{CC}=6.0V$	-	12	21 ns
transition time	t_t	see Figure 5	$V_{CC}=2.0V$	-	14	60 ns
			$V_{CC}=4.5V$	-	5	12 ns
			$V_{CC}=6.0V$	-	4	10 ns
power dissipation capacitance	C_{PD}	$C_L=50pF; f=1MHz; V_i=GND \text{ to } V_{CC}$	-	22	-	pF

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_{en} is the same as t_{PZL} and t_{PZH} .

[3] t_{dis} is the same as t_{PIZ} and t_{PHZ} .

[4] t_t is the same as t_{THL} and t_{TLH} .

[5] C_{PD} is used to determine the dynamic power dissipation(P_D in uW).

$P_D=(C_{PD} \times V_{CC}^2 \times f_i \times N) + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

f_i =input frequency in MHz;

f_o =output frequency in MHz;

C_L =output load capacitance in pF;

V_{CC} =supply voltage in V;

N=number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.

3.3.4 、AC Characteristics 2

(Tamb=-40°C to+85°C,voltages are referenced to GND(ground=0V),unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
74HC125						
nA to nY propagation delay	t_{pd}	see Figure 5	Vcc=2.0V	-	125	ns
			Vcc=4.5V	-	25	ns
			Vcc=5.0V;CL=15pF	-	-	ns
			Vcc=6.0V	-	21	ns
n $\overline{OE}$ to nY enable time	t_{en}	see Figure 6	Vcc=2.0V	-	155	ns
			Vcc=4.5V	-	31	ns
			Vcc=6.0V	-	26	ns
n $\overline{OE}$ to nY disable time	t_{dis}	see Figure 6	Vcc=2.0V	-	155	ns
			Vcc=4.5V	-	31	ns
			Vcc=6.0V	-	26	ns
transition time	t_t	see Figure 5	Vcc=2.0V	-	75	ns
			Vcc=4.5V	-	15	ns
			Vcc=6.0V	-	13	ns
power dissipation capacitance	C_{PD}	CL=50pF;f=1MHz; $V_i = GND$ to Vcc	-	-	-	pF

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_{en} is the same as t_{PZL} and t_{PZH} .

[3] t_{dis} is the same as t_{PIZ} and t_{PHZ} .

[4] t_t is the same as t_{THL} and t_{TLH} .

[5] C_{PD} is used to determine the dynamic power dissipation(P_D in uW).

$P_D=(C_{PD} \times V_{cc}^2 \times f_i \times N)+\sum (C_L \times V_{cc}^2 \times f_o)$ where:

f_i =input frequency in MHz;

f_o =output frequency in MHz;

C_L =output load capacitance in pF;

V_{cc} =supply voltage in V;

N=number of inputs switching;

$\sum (C_L \times V_{cc}^2 \times f_o)$ =sum of outputs.

4 、Testing Circuit

4.1 、AC Testing Circuit

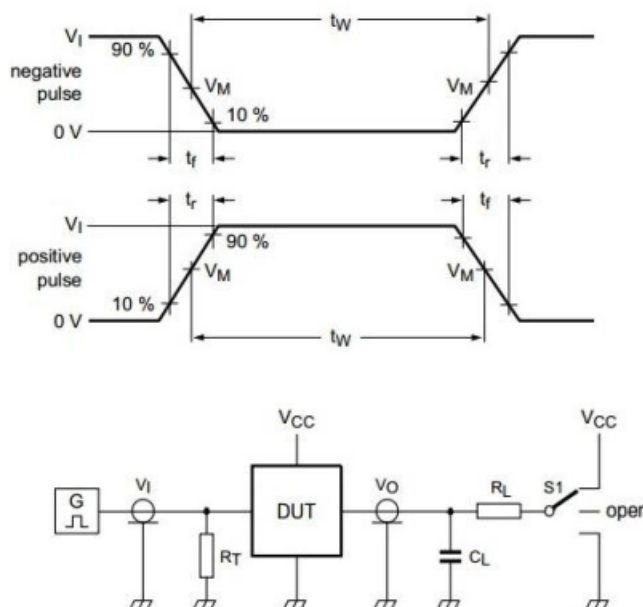


Figure 4. Test circuit for measuring switching times

Definitions for test circuit:

C_L =load capacitance including jig and probe capacitance.

R_T =termination resistance should be equal to the output impedance Z_o of the pulse generator.

R_L =Load resistance.

S_1 =Test selection switch.

4.2 、AC Testing Waveforms

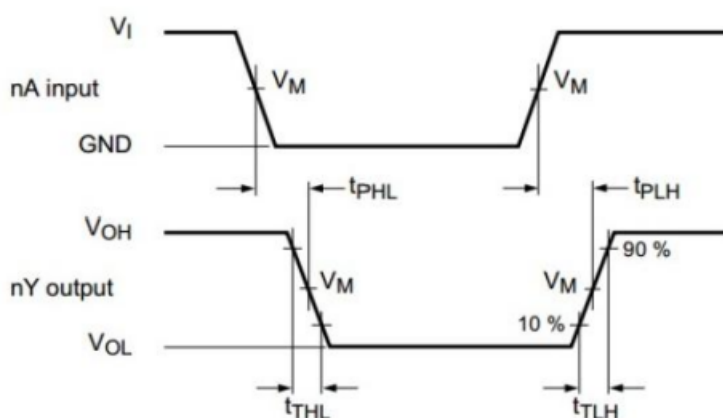


Figure 5. Propagation delay input (nA) to output (nY)

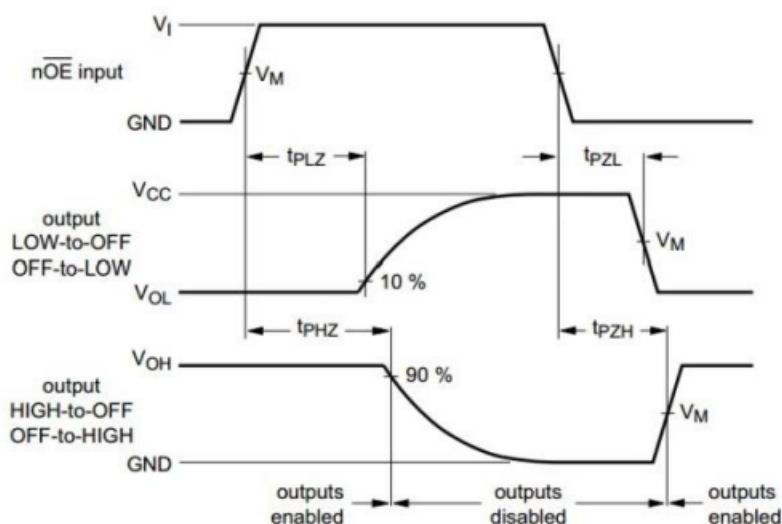


Figure 6.Enable and disable times

4.3、 Measurement Points

Type	Input	Output
	V_M	V_M
74HC125	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

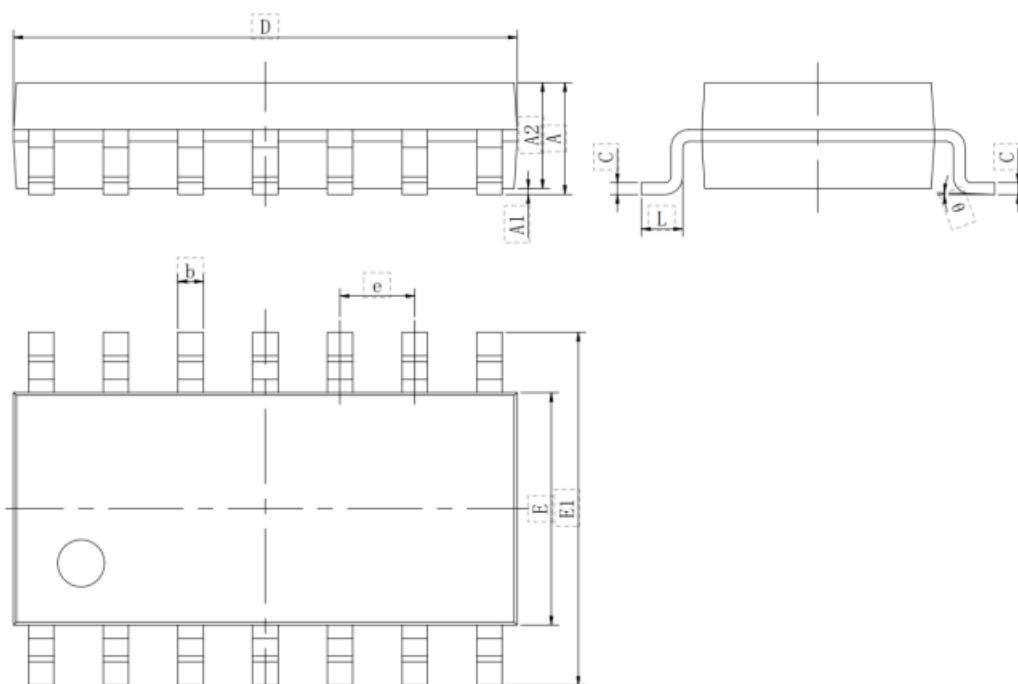
4.4、 Test Data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC125	V_{CC}	6.0ns	15pF, 50pF	1k Ω	open	GND	V_{CC}

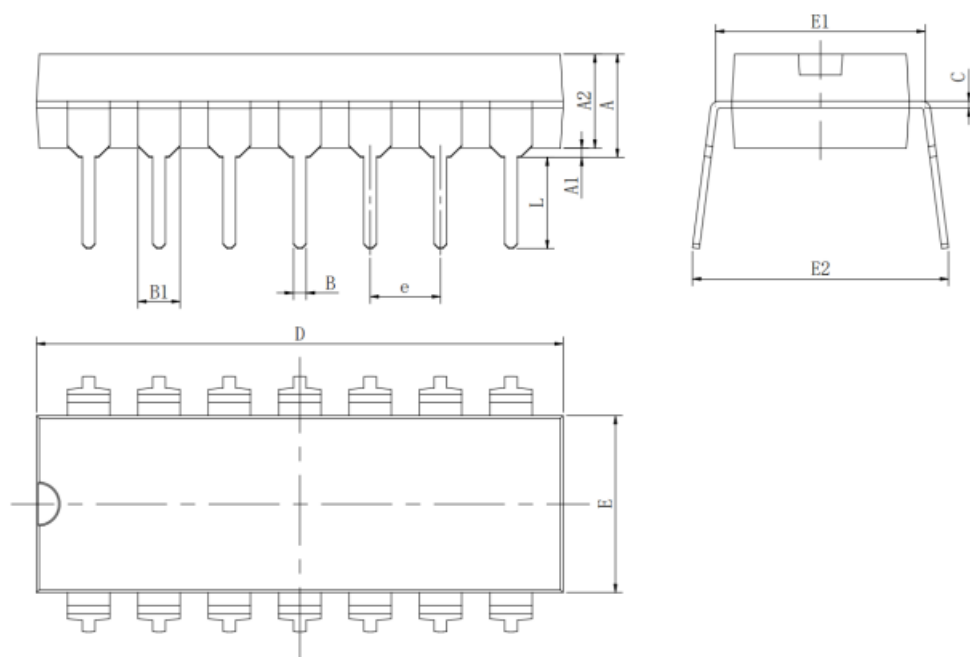
Outline Dimensions

SOP-14

Unit : mm



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	8.360	8.760	0.329	0.345
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0 °	8 °	0 °	8 °

DIP-14
Unit:mm


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	3.710	4.310	0.146	0.170
A1	0.510		0.020	
A2	3.200	3.600	0.126	0.142
B	0.380	0.570	0.015	0.022
B1	1.524(BSC)		0.060(BSC)	
C	0.204	0.360	0.008	0.014
D	18.800	19.200	0.740	0.756
E	6.200	6.600	0.244	0.260
E1	7.320	7.920	0.288	0.312
e	2.540(BSC)		0.100(BSC)	
L	3.000	3.600	0.118	0.142
E2	8.400	9.000	0.331	0.354

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